

Software for Modeling of Long-Term
Growth of Wide-Bandgap Crystals
and Epilayers from Vapor



Virtual Reactor



2018
STR Group, Inc.



Virtual Reactor – Family of Software Tools

STR Virtual Reactor (VR™) is a family of stand-alone 2D software tools designed for the simulation of long-term growth of bulk crystals and epilayers from vapor

Virtual Reactor editions:

- Physical Vapor Transport
 - For growth of SiC: **VR™-PVT SiC**
 - For growth of AlN: **VR™-PVT AlN**
- Hydride Vapor Phase Epitaxy: **HEpiGaNS™**
 - For growth of GaN
 - For growth of AlN and AlGaIn
- Chemical Vapor Deposition
 - For growth of SiC: **VR™-CVD SiC**
- Metal-Organic Chemical Vapor Deposition
 - For growth of GaN, AlN, InGaIn, AlGaIn, and AlInN: **VR™-Nitride Edition**
 - For growth of AIAs, AlP, GaAs, GaP, InAs, InP, AlGaAs, InGaAs, InGaP and AlInGaP: **VR™-III-V Edition**



VRTM-III-V Edition

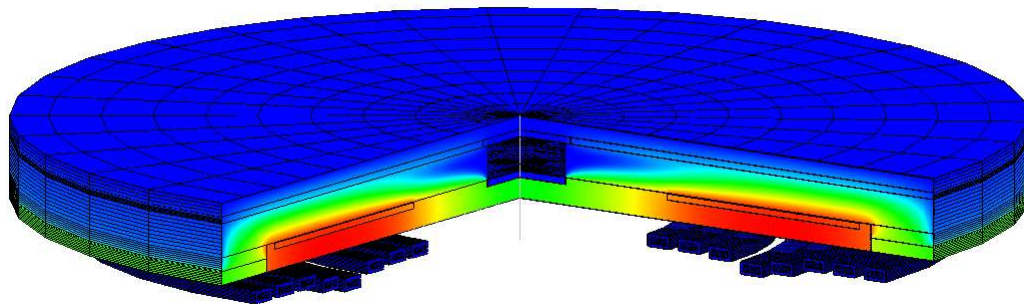
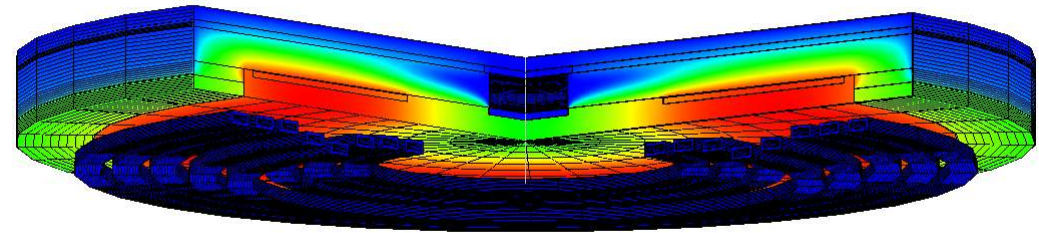
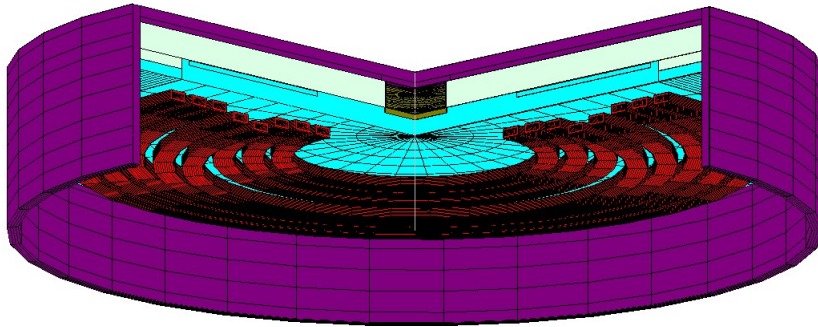
**Software for Modeling of
Epitaxial Growth of Group-III Arsenides and Phosphides by
Metal-Organic Chemical Vapor Deposition**

VR™-III-V Edition

- ✓ AIAs
- ✓ AIP
- ✓ GaAs
- ✓ GaP
- ✓ InAs
- ✓ InP
- ✓ AlGaAs
- ✓ InGaAs
- ✓ InGaP
- ✓ AlInGaP

- Prediction of the growth rate and composition uniformity over the large wafers.
- Parasitic deposition on the walls and injectors (low temperature growth kinetics).

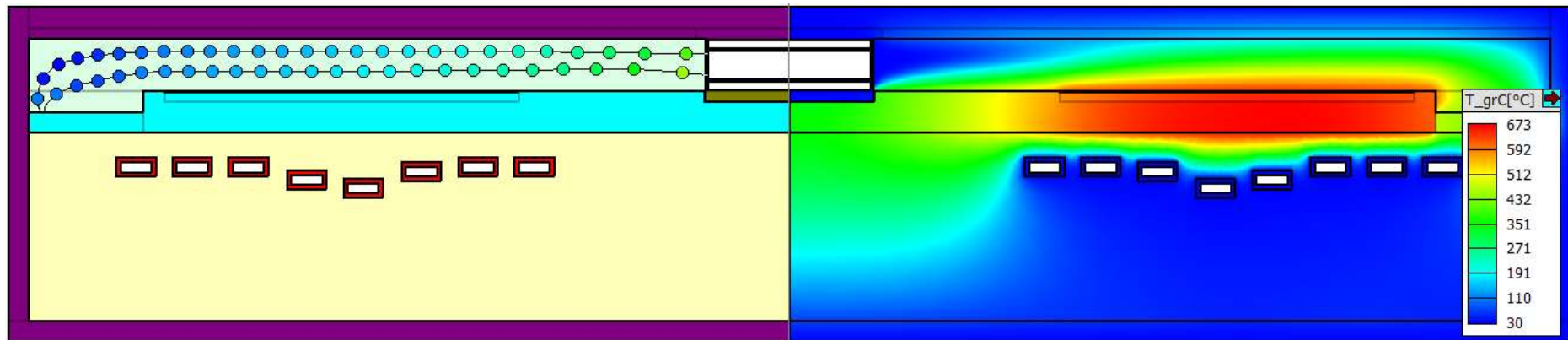
Example of Planetary Reactor with RF Heating



Materials and Temperature Distribution: 3D View

Heat Transfer and the Flow Patterns

- Conductive heat transfer in solid blocks;
- Radiative heat transfer in transparent gas blocks. The view-factor technique is used to model the radiation heat exchange;
- Heat transfer and gas mixture flow, including multi-component diffusion with the Soret effect;
- Heat conductivity and viscosity of the mixture are calculated in terms of molecular kinetic theory. The diffusion of reactive species is modeled using the Wilke approximation.



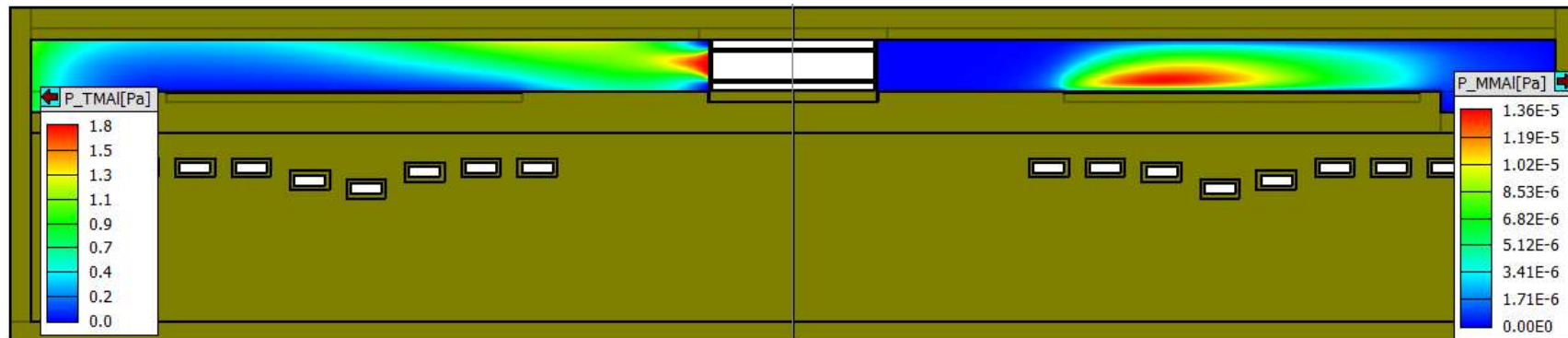
Materials

Stream Traces and Temperature Distribution

2D View

Gas-Phase Chemistry

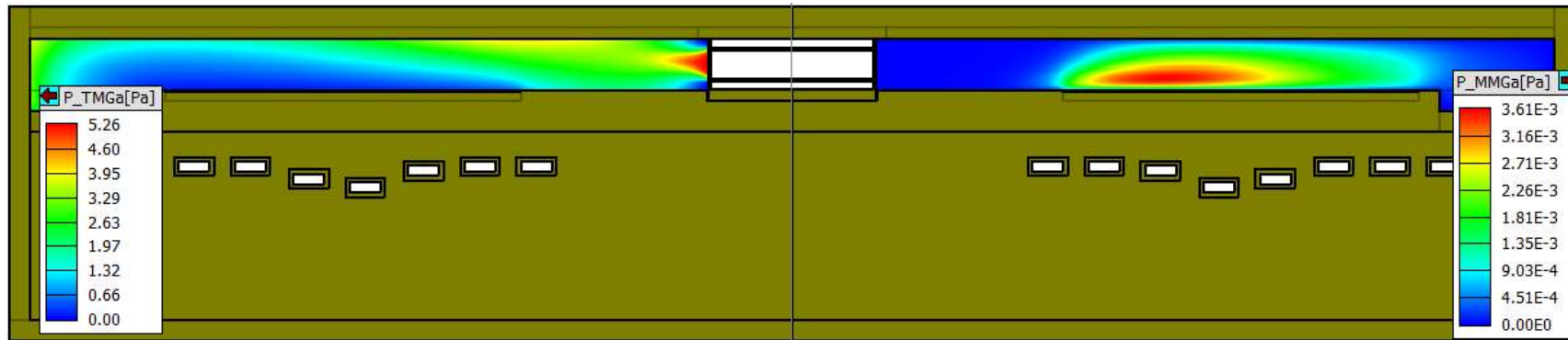
- Gas-phase chemistry is relatively simple compared to VR Nitride Edition (lower temperatures);
- Ga/In/Al chemistry: first-order decomposition of the MO precursors;
- As/P chemistry: actually no or little gas-phase decomposition of group-V hydride precursors;
- Second-order reactions usually can be neglected.



TMAI Partial Pressure

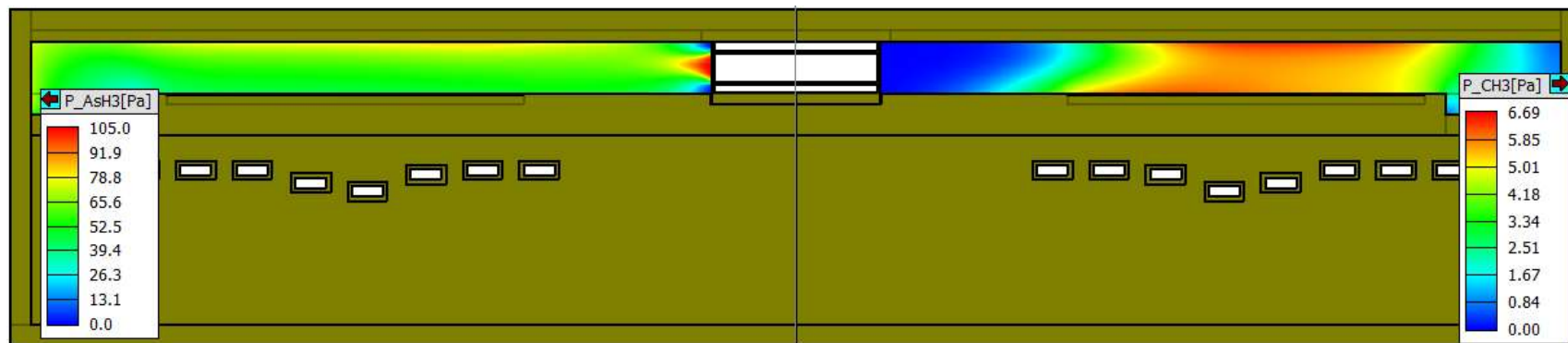
MMAI Partial Pressure

Gas-Phase Chemistry



TMGa Partial Pressure

MMGa Partial Pressure

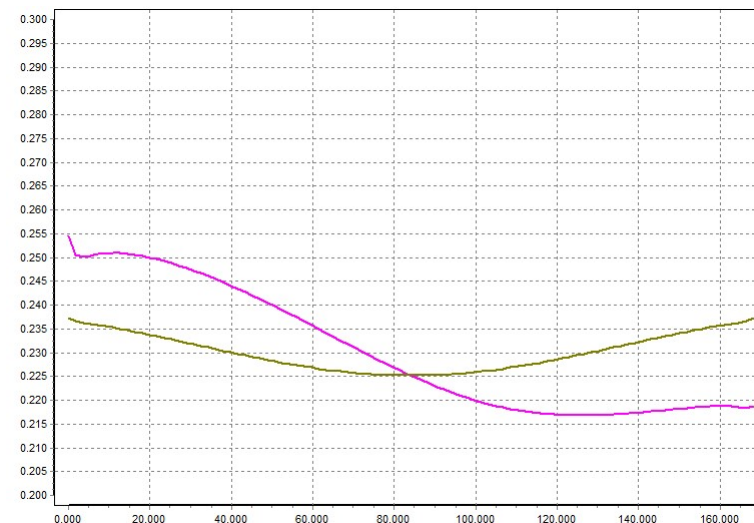
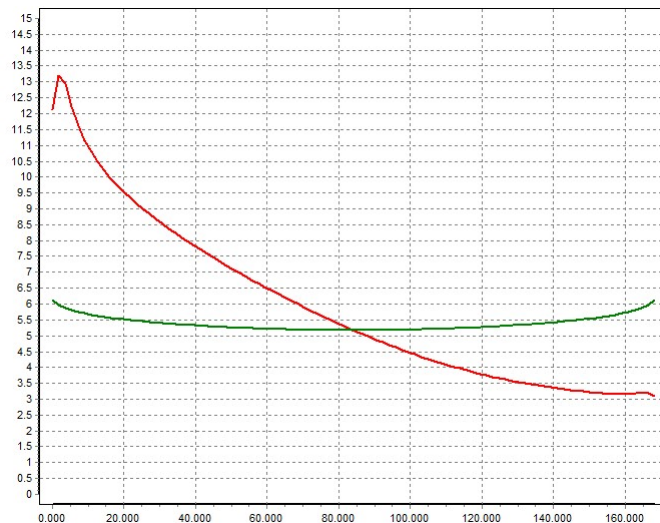


AsH₃ Partial Pressure

CH₃ Partial Pressure

Surface Chemistry

- Ga/In/Al chemistry: adsorption and incorporation of group-III atoms;
- As/P chemistry: adsorption, incorporation, and desorption of excess group-V species as dimers and tetramers;
- Desorption of group-III species is normally weak;
- Low temperatures: strong kinetic limitations, different ranges of temperatures for In-, Ga-, and Al-containing materials



Distribution of instantaneous and rotation-averaged growth rate (left) and AlAs content in $\text{Al}_x\text{Ga}_{1-x}\text{As}$ (right) across the susceptor

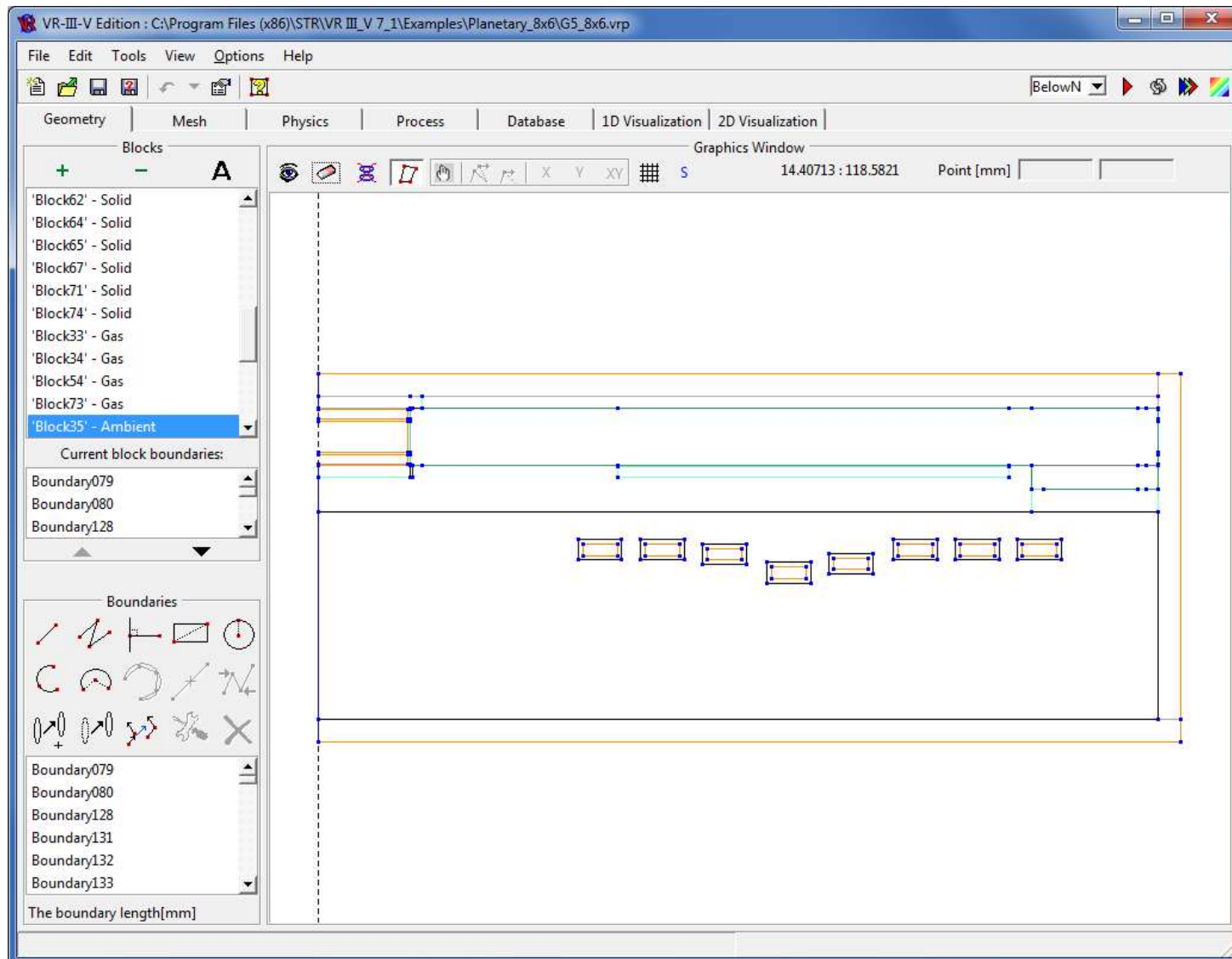


VRTM-III-V Edition

Graphical User Interface

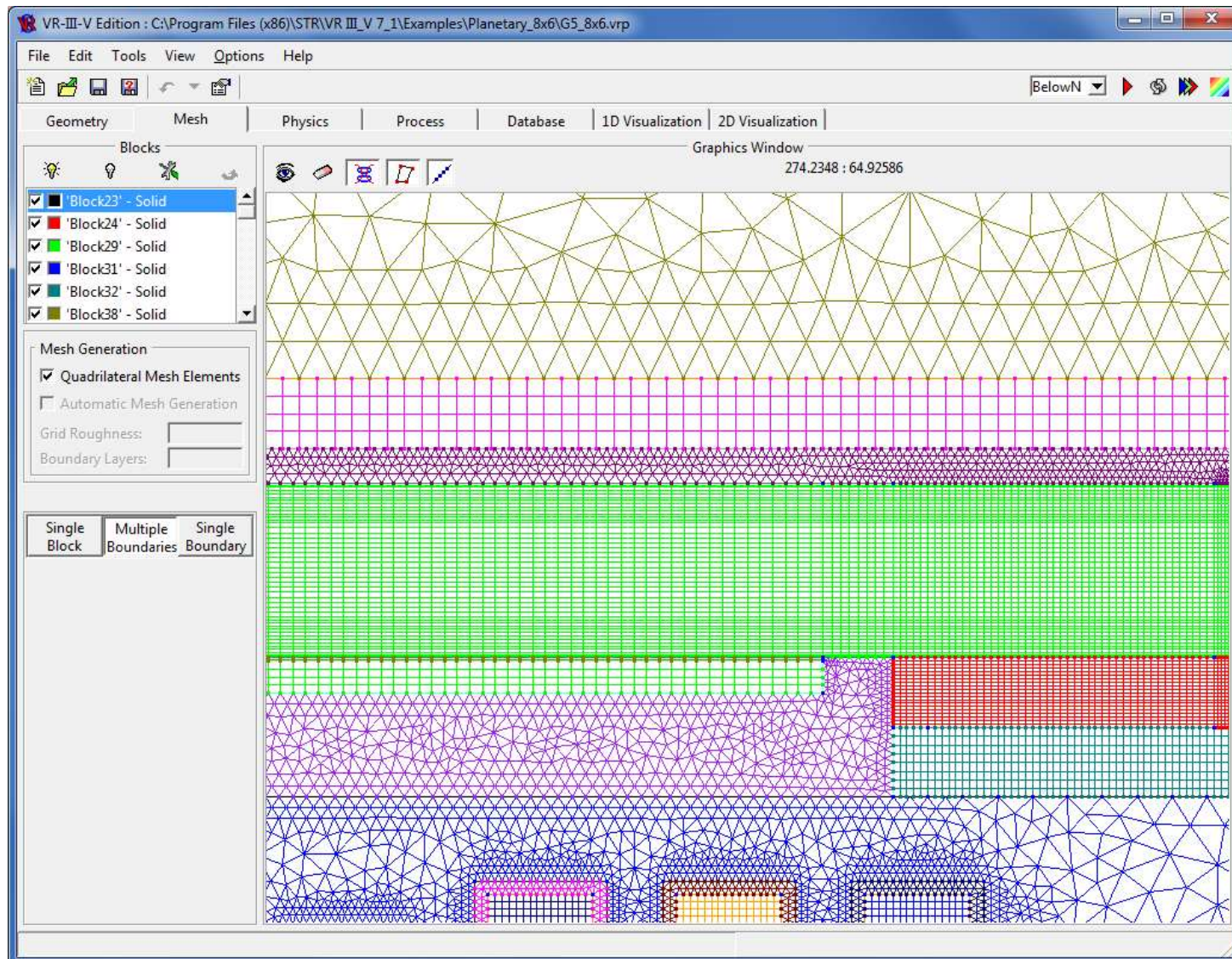


Specification of the Reactor Geometry





Mesh Generation



Specification of the Materials Properties

The screenshot displays the 'Material Properties' dialog box within the VR-III-V Edition software. The dialog is configured for a 'Solid' material named 'R6510 (CZ5)'. The 'Thermal Conductivity' section is active, showing a graph of thermal conductivity λ (in $\frac{W}{m \cdot K}$) versus Temperature (in K). The graph shows a curve that starts at 100 $\frac{W}{m \cdot K}$ at 300 K and decreases to 28.2 $\frac{W}{m \cdot K}$ at 3000 K. The 'Dependence' is set to 'Porous Graphite'. The dialog also includes sections for Porosity, Density, Heat Capacity, and Radiation Properties.

Property	Value
Porosity	0.1
T_0	300
Density ρ_0	100

The graph shows Thermal Conductivity (Y-axis) versus Temperature (X-axis). The Y-axis has labels at 28.2, 64.1, and 100. The X-axis has labels at 300, 1650, and 3000. The curve starts at (300, 100) and decreases to (3000, 28.2).

Specification of the Gas Mixture

The screenshot displays the 'Material Properties' dialog box within the STR software. The dialog is configured for a 'Gas' material named 'Mixt'. It features a table for defining the gas mixture components, with columns for 'Species Name', 'Mass Fraction', and 'Molar Fraction'. The 'Input Variables' section is set to 'Mass Fractions'. The background shows the main software interface with a menu bar, toolbars, and a material database on the right side.

Species Name	Mass Fraction	Molar Fraction
H2	0.659869	0.987264
TMAI	0.00475106	0.000197453
TMGa	0.0265598	0.000691087
AsH3	0.30882	0.0118472



Specification of the Boundary Conditions – AlGaAs Surface

The screenshot displays the VR-III-V Edition software interface. The main window shows a menu bar (File, Edit, Tools, View, Options, Help) and a toolbar. Below the toolbar are tabs for Geometry, Mesh, Physics, Process, Database, 1D Visualization, and 2D Visualization. The left sidebar contains 'Edit Blocks / Boundaries' with 'Block Properties' and 'Boundary Conditions' tabs. Under 'Boundary Conditions', a list of boundaries is shown, with 'Boundary194' selected. Below the list, it indicates 'The boundary length[mm] 170' and 'Multi-Boundary Inlets' including 'Alkyl Inlet' and 'Ammonia Inlet'. The main graphics window shows a 2D visualization of a structure with a red horizontal line. A dialog box titled 'Boundary Conditions: "Boundary194"' is open, showing the 'Solid - Gas Interface' settings. The 'Boundary Type' is set to 'Wall'. Under 'Chemical Parameters', the 'Chemistry Type' is 'HetChem_MOCVD_AlGaAs'. The 'Boundary is Substrate' and 'Substrate is Rotated' checkboxes are checked. The 'Surface Type' is 'AlGaAs'. The dialog box has 'Accept', 'Cancel', and 'Help' buttons.

Specification of the Boundary Conditions – Inlets

The screenshot displays the 'Boundary Conditions: "Boundary434_InletCenter"' dialog box within the VR-III-V Edition software. The dialog is titled "Solid - Gas Interface" and is configured for an "Inlet" boundary type. The "Flow Task" is set to "Inlet Design".

Boundary Type: Inlet

Inlet Design:

- Boundary is an Individual Inlet
- Boundary is a part of Multi-Boundary Inlet

Carrier Gas and Hydride Precursor:

- H2 Flow Rate [slm]: 14
- AsH3 Flow Rate [slm]: 0.3

MO Precursor(s):

TMAI Flow Rate:

- TMAI Flow Rate [sccm]: 5.851805 Use Bubbler

TMGa Flow Rate:

- TMGa Flow Rate [sccm]: 18.78233 Use Bubbler

Bubbler Operating Conditions:

Parameter	TMAI	TMGa
Carrier Flow Rate [sccm]	300	80
Pressure [Torr]	760	760
Temperature [°C]	17	15

TMAI Partial Pressure:

Approximation: Rohm and Haas Units: Torr

$$\log(P_{TMAI_2}) = -\frac{A}{T} + B$$

Parameter	Value
A	2135
B	8.224

TMGa Partial Pressure:

Approximation: Rohm and Haas Units: Torr

$$\log(P_{TMGa_2}) = -\frac{A}{T} + B$$

Parameter	Value
A	1703
B	8.07

Buttons: Accept, Cancel, Help

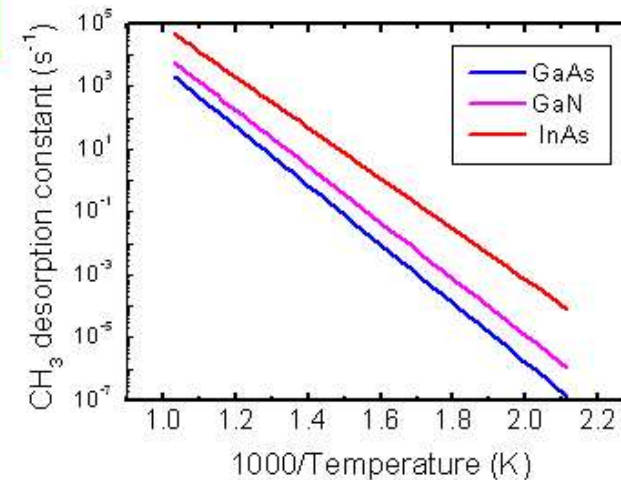
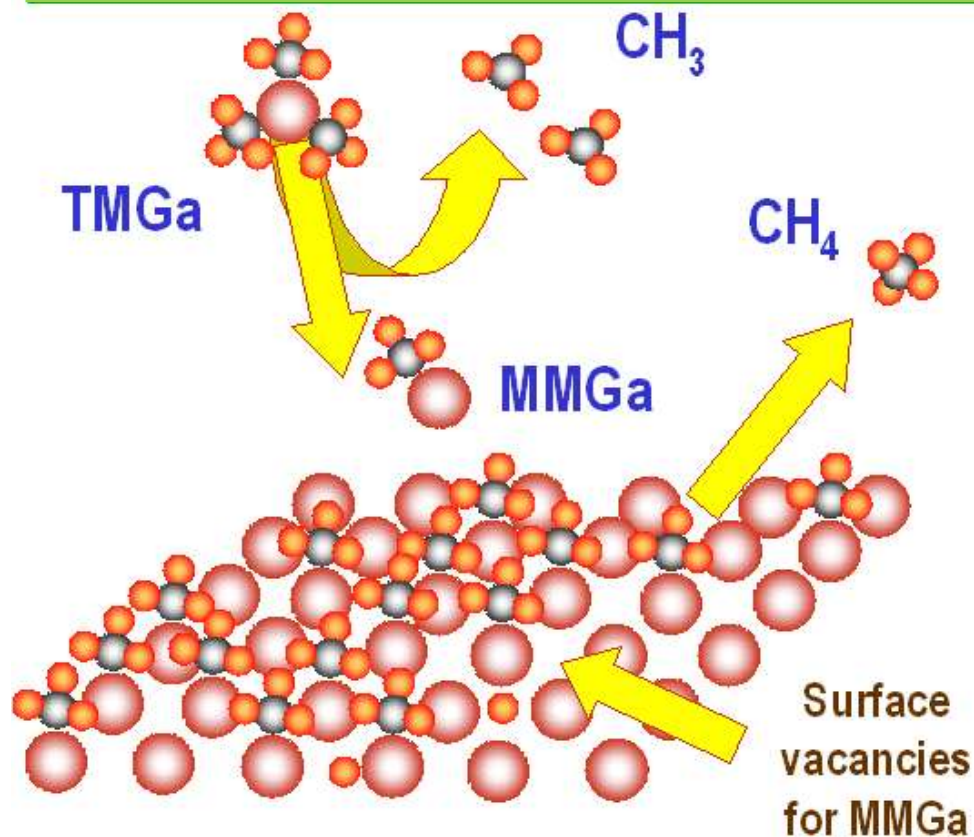


VRTM-III-V Edition

Validation of the Chemical Models

Low-temperature kinetic effects in MOVPE of III-V compounds

Assumption: Hydrocarbon species block free adsorption sites for group-III species

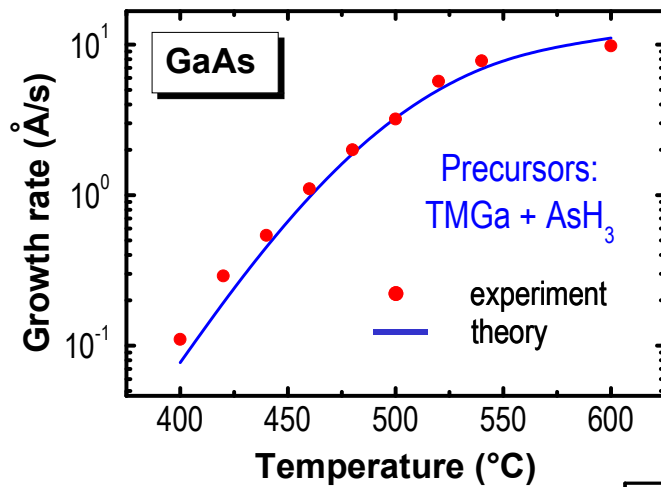


Data on desorption constants from TPD experiments:

J.A.McCaulley et al., *J.Vac. Sci.Technol. A* 9 (1991) 2872

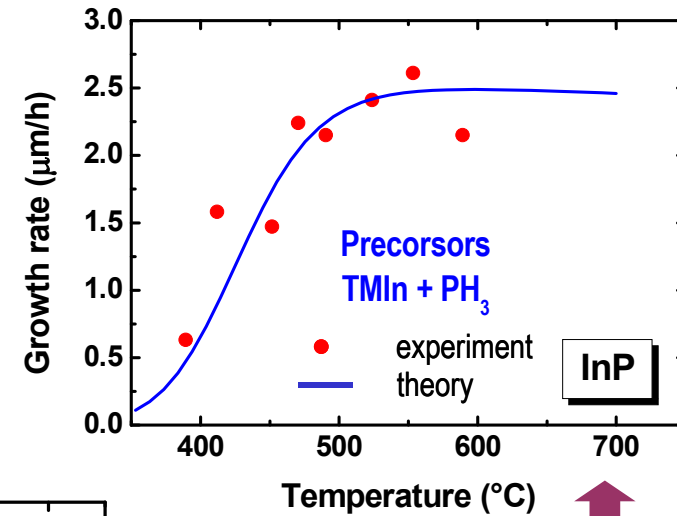
H.-T.Lam et al., *Surf.Sci.* 426 (1999) 199

Low-temperature growth of various III-V compounds



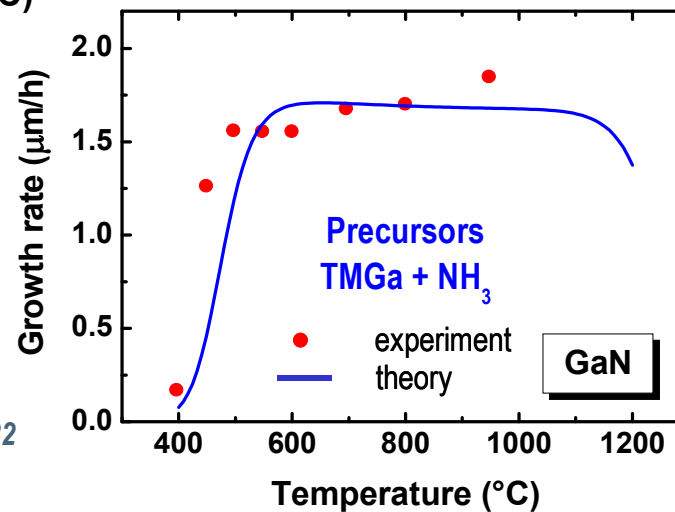
←

Data:
*J.R. Creighton et al.,
 Electrochem. Soc. Proc., 98-
 23, 75 (1999)*



↑

Data: *C.Theodoropoulos et al.,
 J.Electrochem. Soc. 142 (1995) 2086*

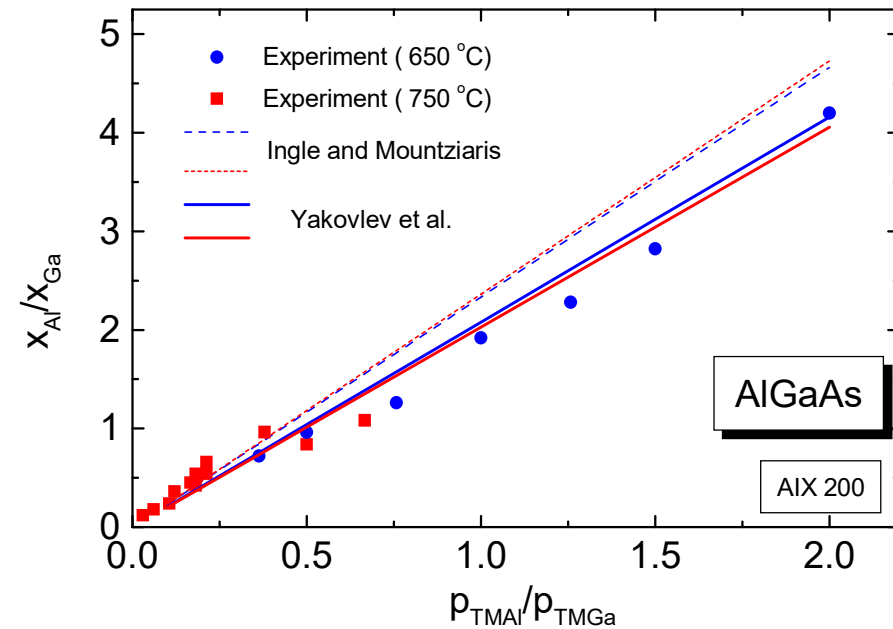
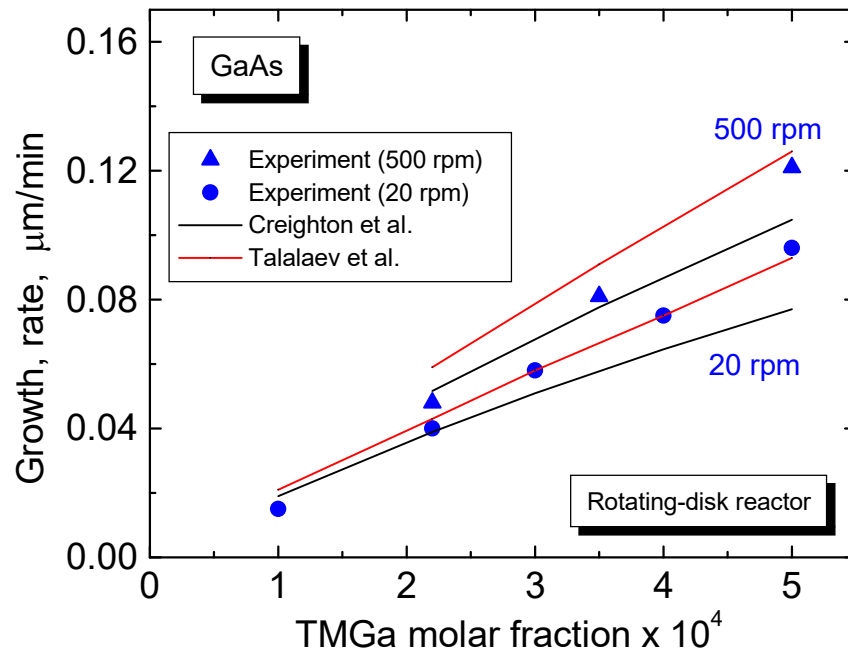


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Data: *C.H. Chen et al, J.
 Electron. Mat., 25, 1004 (1996)*

The model works well for various materials

Growth of arsenides in different reactors

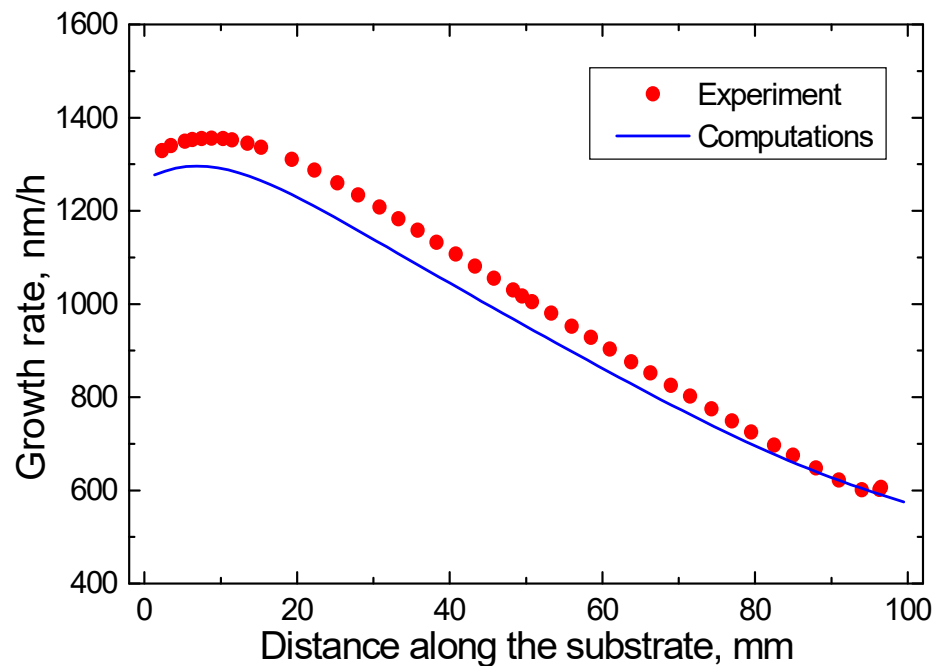


VR-III-V Edition predicts the growth rates and layer compositions without adjusting of any parameter with the accuracy comparable to (and higher than) best kinetic models.

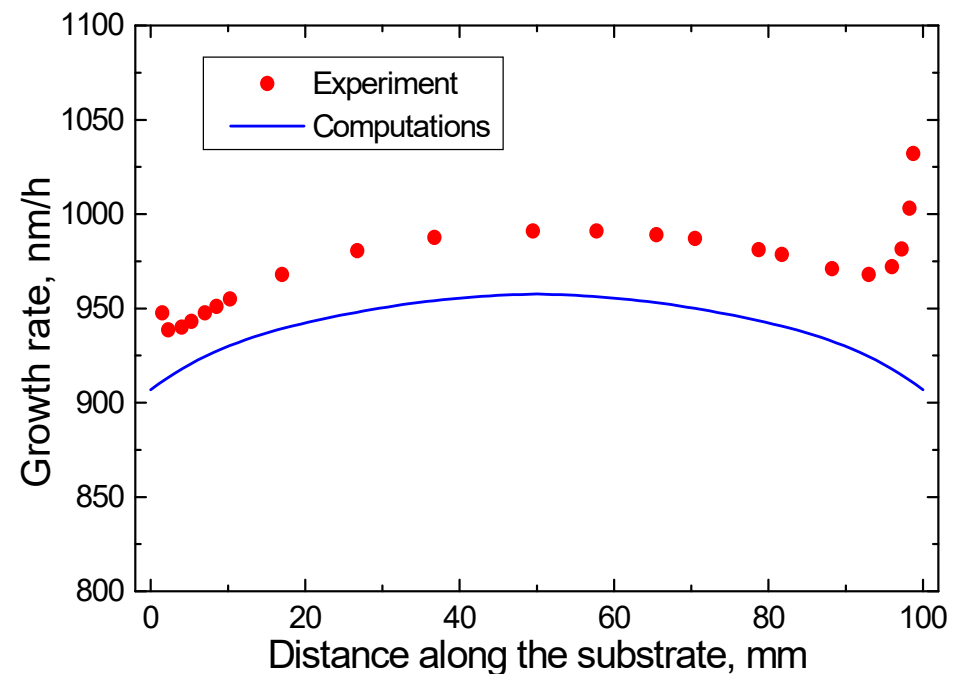


AlGaAs growth rate distribution along the static and rotating wafer

static wafer



rotating wafer



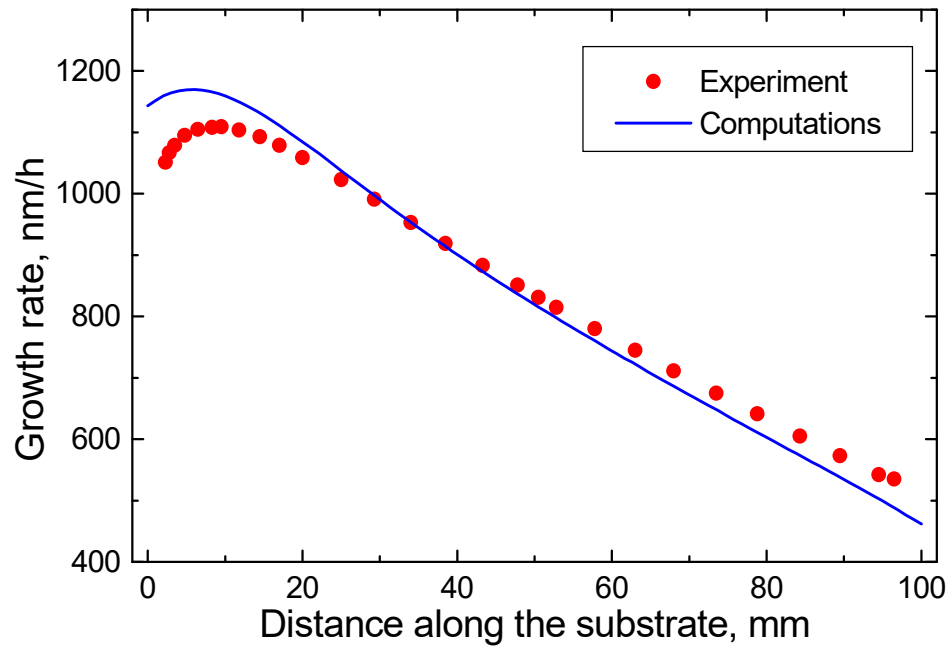
data: E.V. Yakovlev et al., *Electrochem. Soc. Proc.*, 2000-13 (2000) 723.

Computations predict the growth rate with the accuracy about 5 % for the static wafer and about 8 % for the rotating wafer

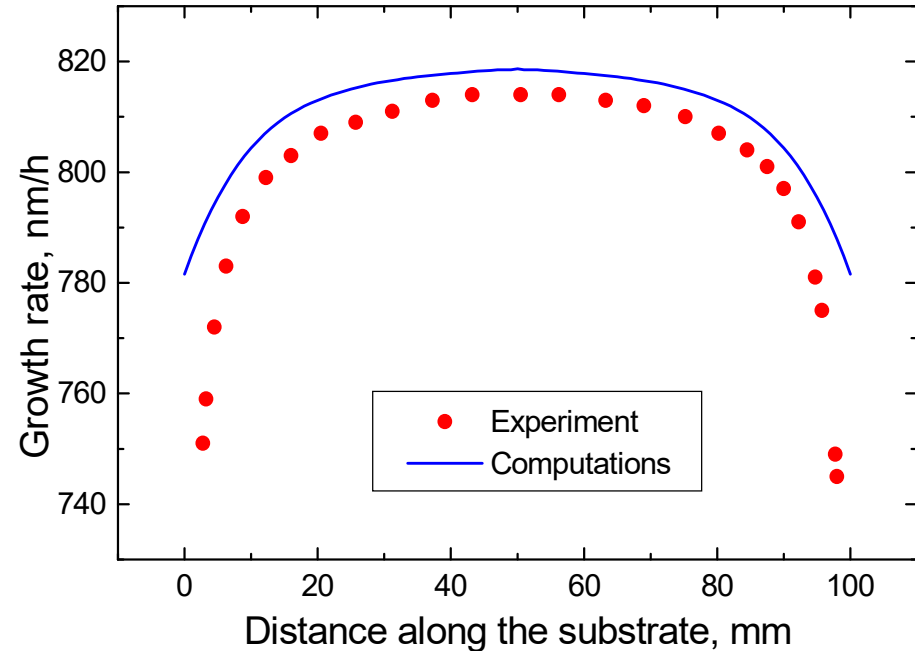


InGaP growth rate distribution along the static and rotating wafer

static wafer



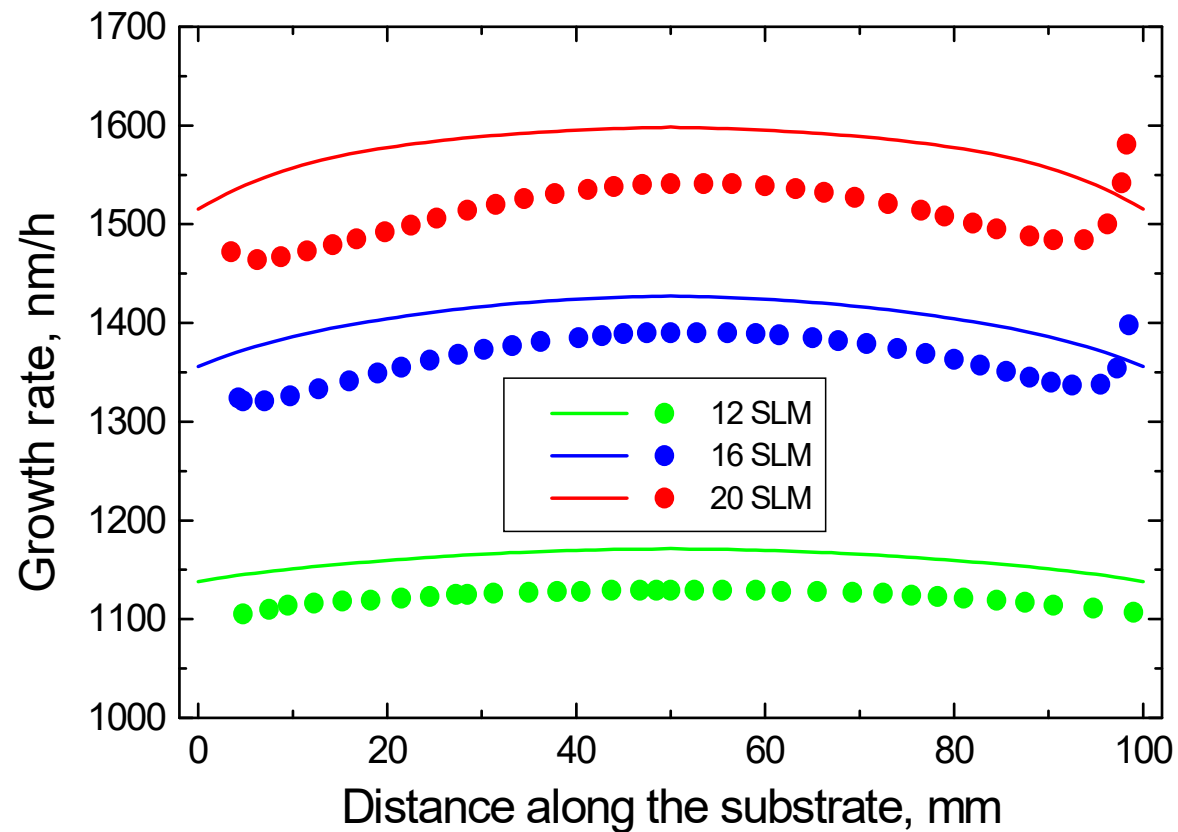
rotating wafer



data: [E.V. Yakovlev et al., *Electrochem. Soc. Proc.*, 2000-13 \(2000\) 723.](#)

Computations predict the growth rate with the accuracy not exceeding 3 % for both static and rotating wafers

Effect of the total flow on the thickness uniformity

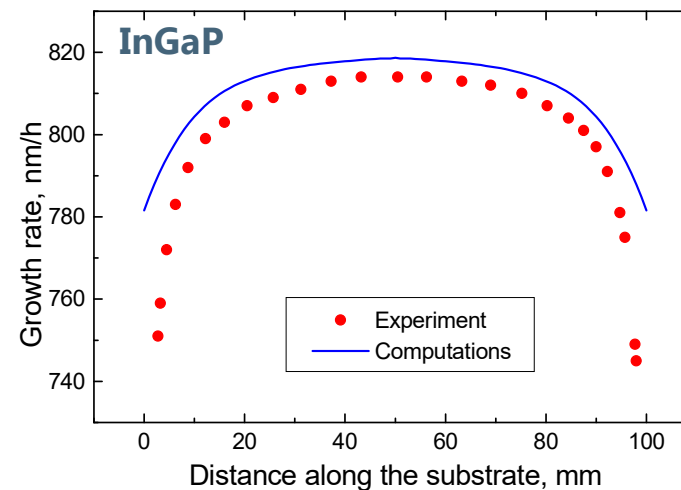
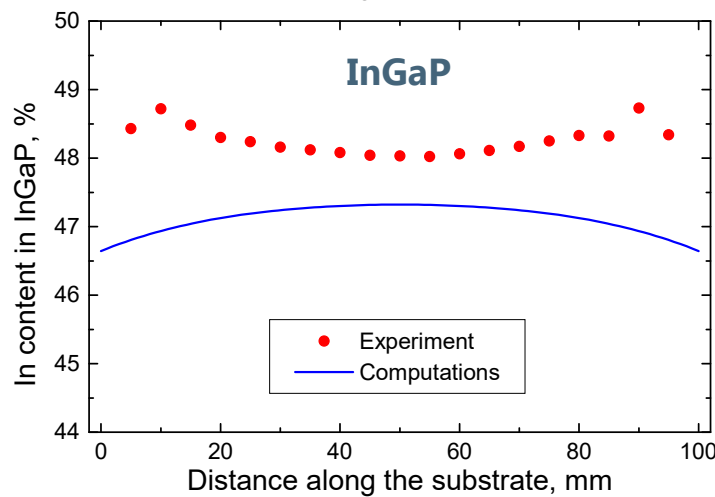
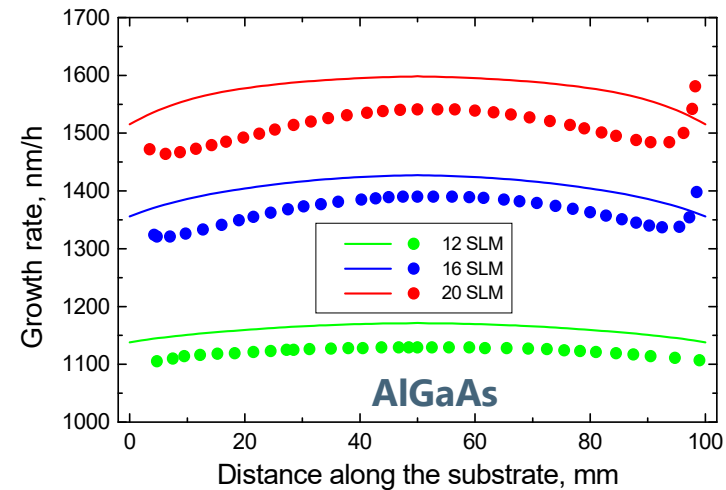
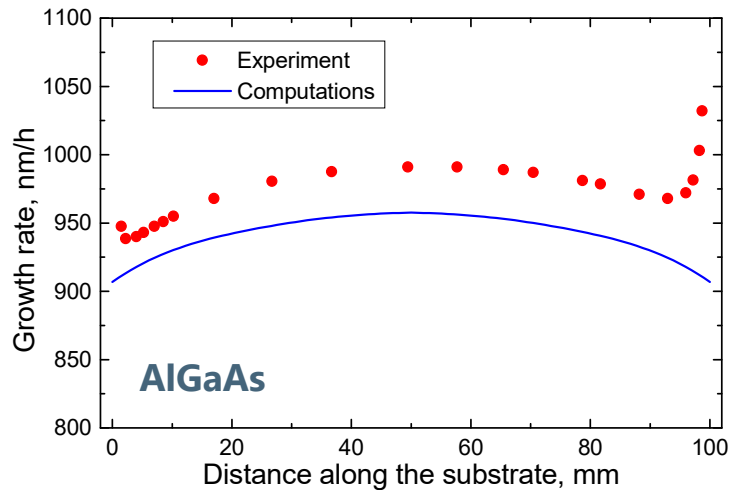


data: T. Bergunde et al., Presented at EWMOVPE-IX (2001).

The effect of the total flow on the growth rate values and uniformity is captured well by the modeling



Model application to the AIX 2400 G3 reactor: summary



Modeling reproduces well both growth rate and layer composition distributions over 4" wafer in the Planetary reactor



- ✓ Consulting service & software support:
vr-support@str-soft.com

- ✓ Information on commercial software
www.str-soft.com

Detailed info is supplied to VR customers and is available upon request:

- Demo version
- Physical summary
- Code description
- GUI manual
- VR tutorials



Some VR users in Europe



BEGA

ОТКРЫТОЕ АКЦИОНЕРНОЕ ОБЩЕСТВО «КОМПАНИЯ РАДИОТЕХНИКИ «ВЕГА»
JOINT-STOCK COMPANY «RADIO ENGINEERING CORPORATION «VEGA»



Some VR users in South-East Asia

NIPPON STEEL



Fujikura



BRIDGESTONE



ShinEtsu

SHOWA DENKO



SUMITOMO ELECTRIC



SKC

DENSO



OCI



Institute of Semiconductors
Chinese Academy of Sciences